Training Notification Form, IIT Delhi

Company Overview

Name: Micron Technology

Website: www.micron.com

Company Type: Core (Technical)

Description: Micron Technology, Inc. is an American producer of computer memory and computer data storage including dynamic random-access memory, flash memory, and USB flash drives. It is headquartered in Boise, Idaho. Its consumer products are marketed under the brands Crucial[3] and Ballistix.

Project Details

Designation: Intern- Global AT-PDE (TDNE)

Type: Core (Technical)

Location: Hyderabad

Project Details: About Micron: Over 40 years, Micron's memory and storage solutions have been foundational to innovations that have transformed the world in countless ways. Our technology and expertise are core to computers that boot up in an instant and work harder and faster; mobile phones with brilliant screen resolution and longer battery life; and new business models that are disrupting entire industries faster than ever — such as entertainment, manufacturing, and finance. As a global leader in memory and storage solutions, we are transforming how the world uses information to enrich life by enabling technologies to collect, store and manage data with unprecedented speed and efficiency.

Culture at Micron: From a four-person semiconductor design company in the basement of a Boise, Idaho, dental office in 1978 to a global, multicultural organization — advocating for social justice and striving to tip the scales toward a more equitable and sustainable world, Micron's culture is what drives its innovation and market leadership. Our diversity, equality, and inclusion (DEI) programs are globally recognized and locally designed. Likewise, we also offer a diverse set of learning options — from self-directed, winding pathways of knowledge to rigorous academic sprints. We nurture a culture that is fair, fearless, and fun that works to enhance personal and professional development at every level.

About profile – Intern- Global AT-PDE (TDNE)
Do you believe that data provides groundbreaking insight? Do you see data as an asset that builds a competitive advantage? Do you accept the challenges of working with in-memory technologies to construct and deploy data assets delivering insights for business value? Great…so do we!
Micron Technology operates in a highly competitive industry where innovation depends on forward-thinking minds extracting fresh insights from an ever-expanding data universe. We operate in a diverse, collaborative space where problem solving is a team sport and creative solutions are recognized and rewarded. Does this sound like the right team for you? Good news. We're hiring!

As the leader in innovative memory solutions, Micron is helping the world make sense of data by delivering technology that is redefining how the world uses information. Through our global brands — Micron, Crucial and Ballistix — we offer the industry's broadest portfolio. We are the only company manufacturing today's major memory and storage technologies: DRAM, NAND, and NOR. Our solutions are purpose built to leverage the value of data to unlock financial insights, accelerate scientific breakthroughs and improve communication around the world.

Job Description

This role is for an Intern Process Data Simulation (PDS) Engineer within Package Development Engineering (PDE) team. PDE PDS has been Center of Excellence (COE) for digital twins for backend process simulations. The team develops validated simulation methodologies and Digital Twins to help in cycle time reduction and quality/yield improvements.

Roles & responsibilities can include but are not limited to:

• Partner with process engineering teams to understand the packaging process, develop analysis models.

• Structural analysis using Finite Element Methods or hand calculations of the various process involved in semiconductor packaging for predicting and enhancing the performance.

• Guide test vehicle development to improve simulation correlation to empirical data. Develop test plan wherever necessary to verify the simulation models and validate analysis approach in correlation with test outcomes.

• Participates in development of simulation modeling methodologies in Structural, Thermal, Thermo-Structural and Multiphysics domain.

• Deploys developed simulation methodologies to strengthen "Analysis First" strategy and develop Digital Twins.

• Communicate FEA analysis results to process engineers and provide technical and/or design recommendations.

• Solid knowledge through coursework, or experience in solid mechanics, structural dynamics, finite element methods.

• Ability to draw free body diagrams and perform hand calculations.

• Experience or knowledge through coursework on modeling non linearities, material properties and material property test methods

• Knowledge of one or more software's like Ansys, Abaqus, COMSOL and Simcenter

• Strong oral and written communication skills.

Education Requirement & eligibility:

• Students pursuing B.Tech/ M.Tech/ MS or PhD in Mechanical Engg/ Aerospace Engg / Applied Mechanics

• CGPA requirements = 7.0 CGPA & Above

Location:
Hyderabad

Stipend Details

Stipend:	50,000 INR Per Month
Accommodation:	Yes
Travel Expenses:	No

Selection Process

Resume Shortlist:	Yes
Written Test:	No
Online Test:	Yes
Group Discussion:	No
Personal Interview:	Yes
No. of Offers:	1

Eligibility

Diversity Recruiting:	No
Eligible Years:	Graduating in 2025 (Pre-Final Year Students) - B.Tech / Dual / Master's
Eligible Departments:	B.Tech in Engineering Physics, B.Tech in Engineering and Computational Mechanics, B.Tech in Mechanical Engineering, B.Tech in Production & Industrial Engineering